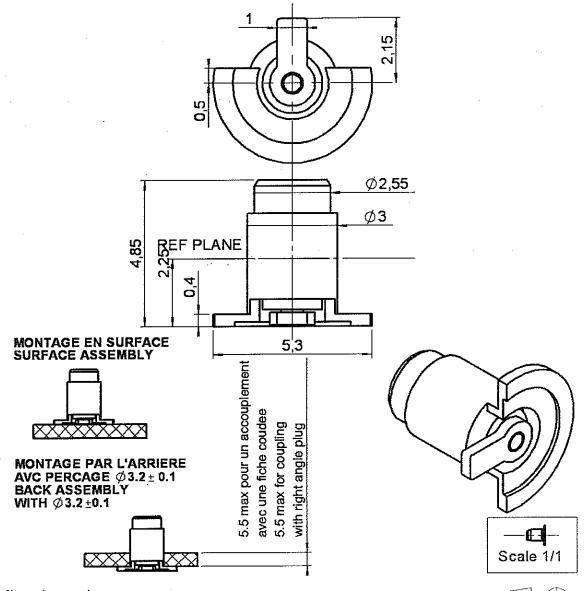
REEL OF 100

R199.005.820

Series: MC-CARD



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BRASS BERYLLIUM COPPER - PTFE -	GOŁD 0.5 OVER NICKEL 2 GOŁD 1.3 OVER NICKEL 2 -
- -	-	-

Issue: 0420 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



TECHNICAL DATA SHEET

SMT RECEPTACLE

REEL OF 100

R199.005.820

Series: MC-CARD

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

1.15 +

ENVIRONMENTAL

Impedance

50 Ω

Frequency

0-8 GHz

VSWR

0.015 x F(GHz) Maxi

Insertion loss RF leakage

0.07 $\sqrt{F(GHz)}$ dB Maxi - - F(GHz)) dB Maxi

Voltage rating

170 Veff Maxi

Dielectric withstanding voltage Insulation resistance

500 Veff mini

- (

5000 MΩ mini

Operating temperature

-65/+165 °C

Hermetic seal

NA Atm.cm3/s

Panel leakage

NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force - Mating end

NA N mini

Axial force – Opposite end

NA N mini

Torque

NA N.cm mini

Recommended torque

Mating

NA N.cm

Panel nut

NA N.cm

Mating life

0 Cycles mini

Weight

0.160 g

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MC-CARD SERIES - INFORMATIONS SOLDER PROCEDURE OF MC-CARD RECEPTACLES IN INDUSTRIAL ENVIRONMENT

 Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

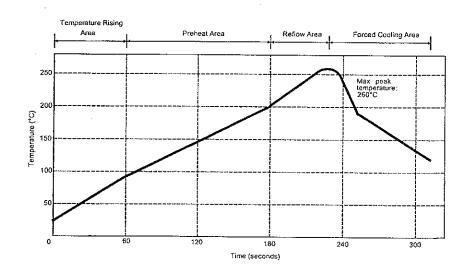
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

A video camera is recommended for positioning of the component.

Adhesive agents must not be used on the receptacle.

- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit	
Temperature rising Area	1 - 4	°C/sec	
Max Peak Temperature	260	°C	
Max dwell time @260°C	10	sec	
Min dwell time @235°C	20	sec	
Max dwell time @235°C	60	sec	
Temperature drop in cooling Area	-1 to - 4	°C/sec	
Max dwell time above 100°C	420	sec	

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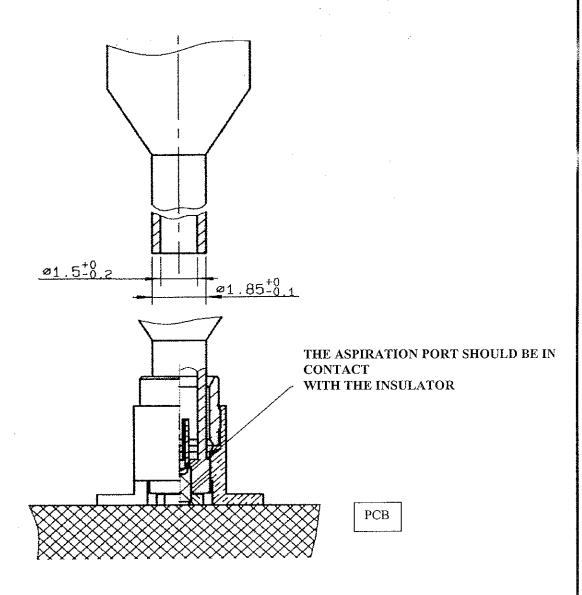
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MC-CARD SERIES - INFORMATIONS

ASPIRATION PORT



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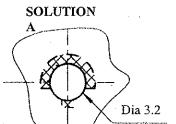


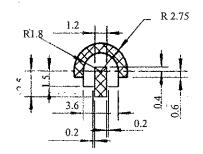
REEL OF 100

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Series: MC-CARD

MC-CARD SERIES -









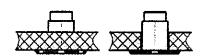
Pattern



Land for solder paste

Receptacle back planting Same printed circuit that B + Dia 0.13

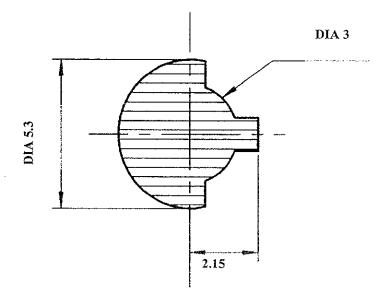
SOLUTION



COPLANAR LINE

Pattern and signal are on the same side Thickness of PCB is the epoxy resin of glass fabric bacs(Er=4.8) The solder resist should be printed exept for the land pattern on the PCB

SHADOW OF MC-CARD RECEPTACLE FOR VIDEO CAMERA



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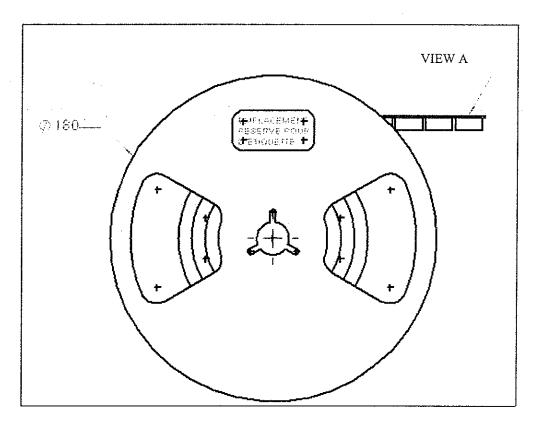


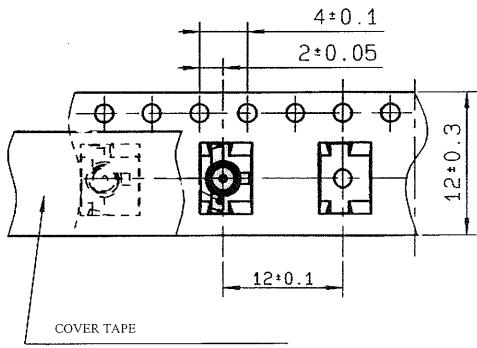
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MC-CARD SERIES INFORMATION





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